PRESS RELEASE

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TechSearch International Analyzes Hybrid Bonding Developments and Panel Market Growth

In its latest Advanced Packaging Update, TechSearch International provides an update on developments in hybrid bonding including applications, technical challenges, and proposed solutions. The report focuses on hybrid bonding for high-performance applications.

TechSearch International examines the growth in advanced packaging for high-performance computing (HPC) and analyzes assembly revenue. AI inferencing and training hardware, including high bandwidth memory (HBM), accounts for the majority of the assembly value. The HPC advanced packaging assembly market is defined as assembly of AI training and inferencing, server, and high-end network switch packages. Assembly revenue for HBM is included. OSAT financials are also highlighted in the report.

A special section of the report analyzes the fan-out panel market by dividing it into standard-density and high-density panels. Applications are presented and market forecasts are provided for both. Company activities are highlighted.

The report includes a section on RF front-end packaging developments in mobile devices with highlights from our teardowns.

The latest Advanced Packaging Update is a 67-page report with full references and an accompanying set of 77 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 22,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch International at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on LinkedIn.

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